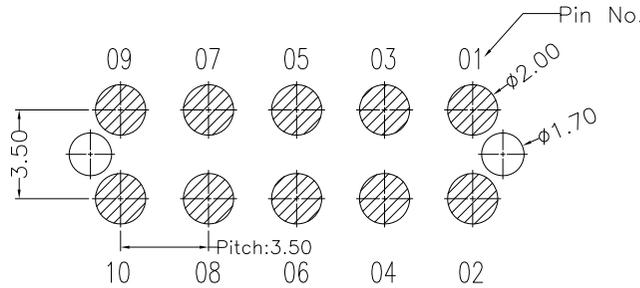
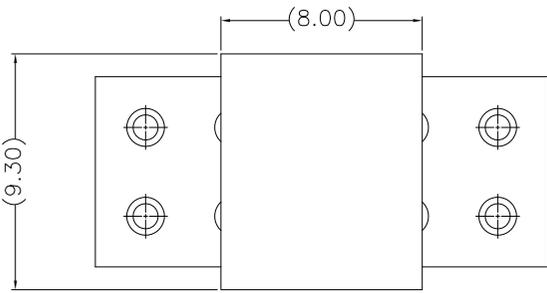
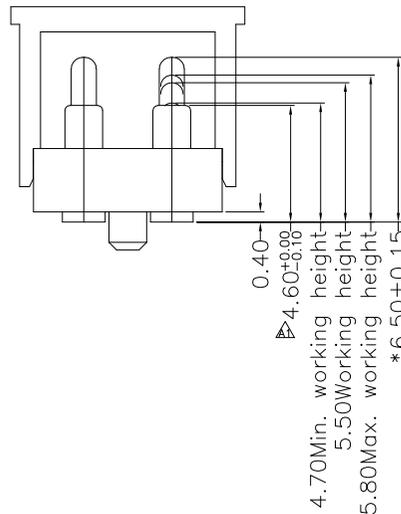
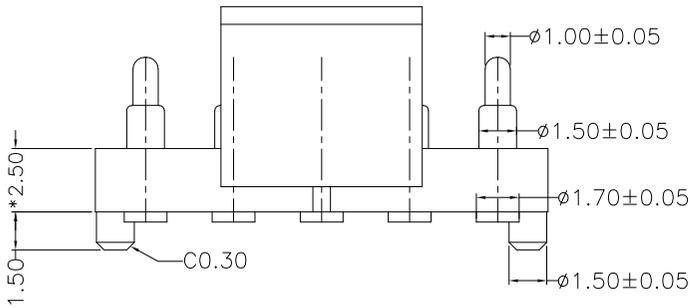
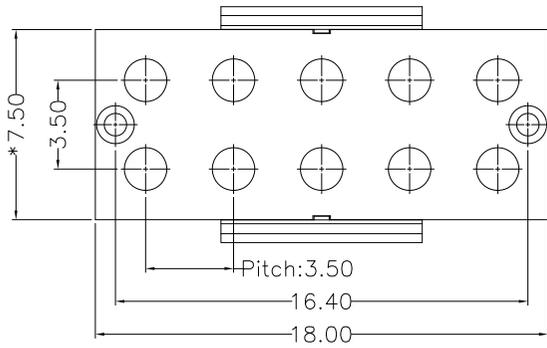


GP Component

| REV. | ECN NO. | LOCATIONS | DESCRIPTION | DATE | DESIGN |
|------|---------|-----------|----------------------------|------------|-----------|
| A0 | | | Initial | 2025/03/07 | Zonlin Wu |
| A1 | | | Size change/current change | 2025/06/06 | Zonlin Wu |

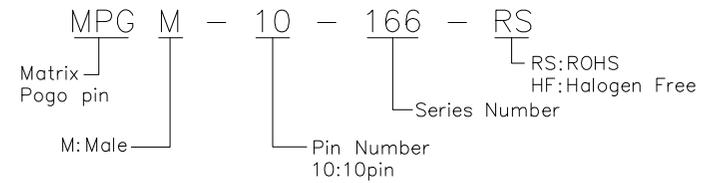


RECOMMENDED PCB LAYOUT
Tolerance: ±0.05mm

Notes:

- Material**
Plunger&Barrel: Lead free Brass ,Plated Gold flash(1u"min.) over 50-120u"Ni
Spring: SUS304
CAP/Housing:PA9T Black UL94 v-0
- Mechanical**
Normal Spring force: 100g±20g at working height
Durability: 10, 000Cycles min
- Electrical**
Rated Current&Voltage: DC 12V,1.5A Max.
Contact Resistance: 100mohm max at working height(quiescence)
- Operating Temperature:** -40 to +85°C
Humidity Range:10%RH to 90%RH
Solder Temperature: 260°C±5°10s±2s
Salt Spray:24H,No Corrosion
Lead free ,RoHS compliant
- Packing:**REEL+Carrier
- To ensure the best usage,please operate it based on the working height
Based on the engineering drawings ,shall not exceed the min.working height
- "*"is the key dimensions .

MATRIX PART NO:



Matrix Electronics Co., Ltd

| | | | | |
|---|--------------------------------|----------------------|---------------------------|----------------|
| TOLERANCE: 0~6 ±0.10mm >6~30 ±0.20mm >30~120 ±0.30mm >120 ±0.50mm ANGLE ±5° | DESIGN BY : Zonlin Wu | DATE : 2025/06/06 | PART NAME: Pogopin.com | |
| | CHECKED BY: Hanson Huang | DATE : 2025/06/06 | PART NO. | MPGM-10-166-RS |
| UNIT: mm [inch] | APPROVED BY1: Richard Hsieh | DATE : 2025/06/06 | MOLD NO. | NA |
| | APPROVED BY2: Richard Hsieh | DATE : 2025/06/06 | DRAW NO. | |
| SCALE:1:1 | SIZE:A4 | | SHEET NO. | 1 OF 1 |